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09/959466

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To the Honorable Commissioner of Patents

101941190

the attached original documents or copy thereof.

1. Name of conveying party(ies):

TAKIKAWA, Kumiko
TANAKA, Satoshi

10/26/01

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date: September 5, 2001

2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Address: 6, Kanda Surugadai 4-chome

Chiyoda-ku

City: Tokyo

State/Prov.:

Country: Japan

ZIP:

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: September 5, 2001

Patent Application No.

Filing date

B. Patent No.(s)

10/30/2001 UEDUVIJE 00000131 09959466

02 FC:581

40.00 DP

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mitchell W. Shapiro

Registration No. 31,568

Address: Miles & Stockbridge P.C.

1751 Pinnacle Drive

Suite 500

City: McLean State/Prov.: VA

Country: USA ZIP: 22102-3833

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41): \$ 40.00

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mitchell W. Shapiro

Name of Person Signing

Mitchell W. Shapiro

Signature

October 26, 2001

Date

2

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PATENT
REEL: 012436 FRAME: 0638

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

INTEGRATED CIRCUIT WITH PROTECTION AGAINST ELECTROSTATIC DAMAGE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Kimiko Takikawa

4/5/2001

2) Satoshi Tanaka

9/5/2001

3) _____

4) _____

5) _____

6) _____

7) _____

8) _____

9) _____

10) _____
